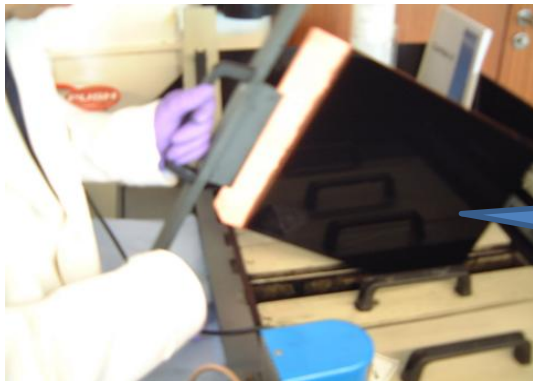


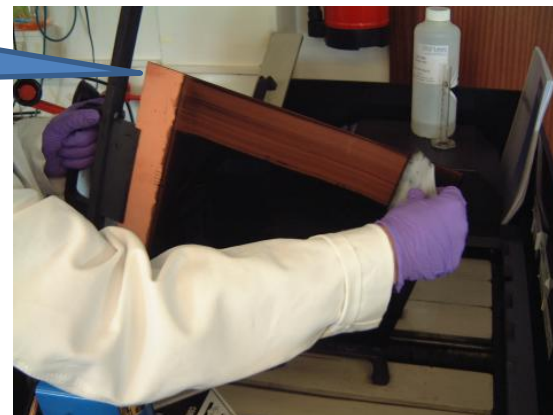
LPKF ViaCleaner

To remove the activator from every
copper surface



Immediately after activating the board, it has this aspect

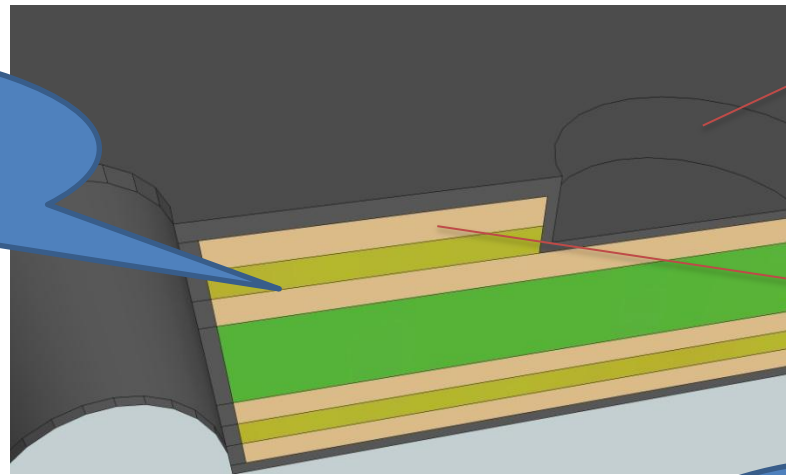
With the squeegee we clean the surface of the PCB from ACTIVATOR rests and give it back to the pool



but these grooves are really horrible

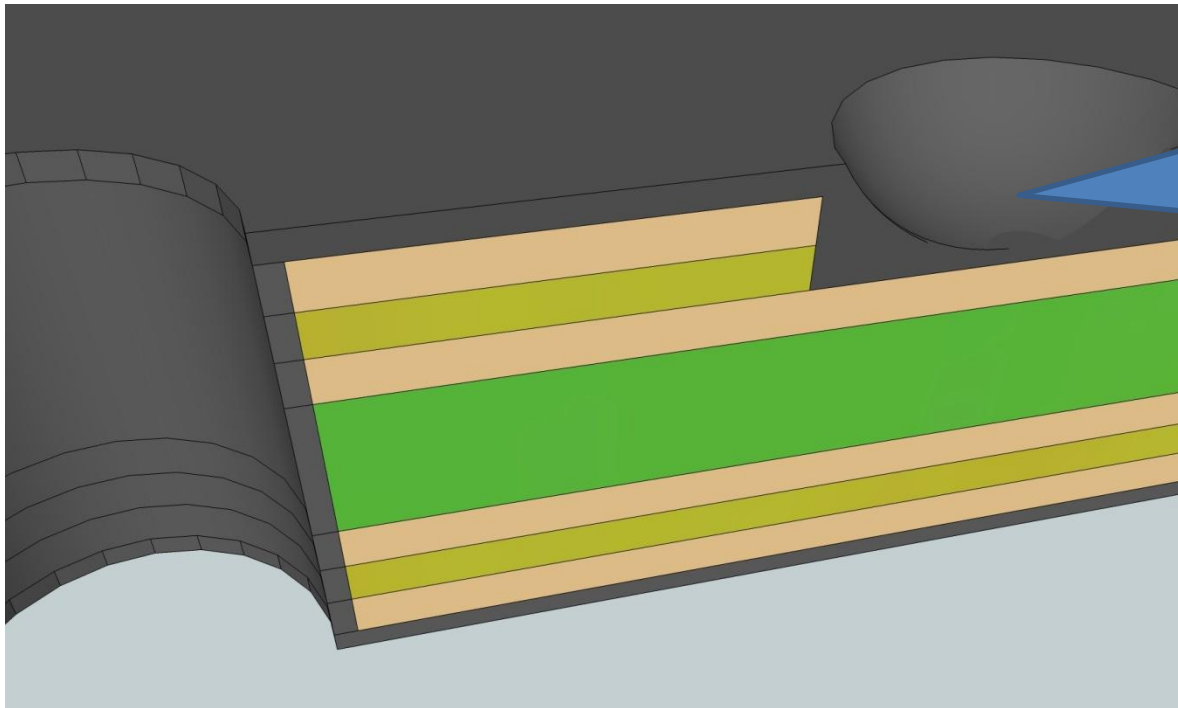
LPKF ViaCleaner

If we could magnify it, the aspect would be very simmilar to this



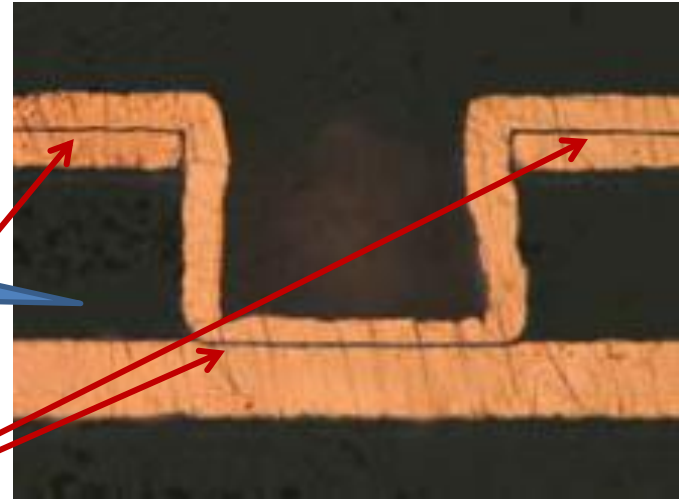
Activator

Copper



For very small holes, it could be even worse !

After the galvanic step it could look like that

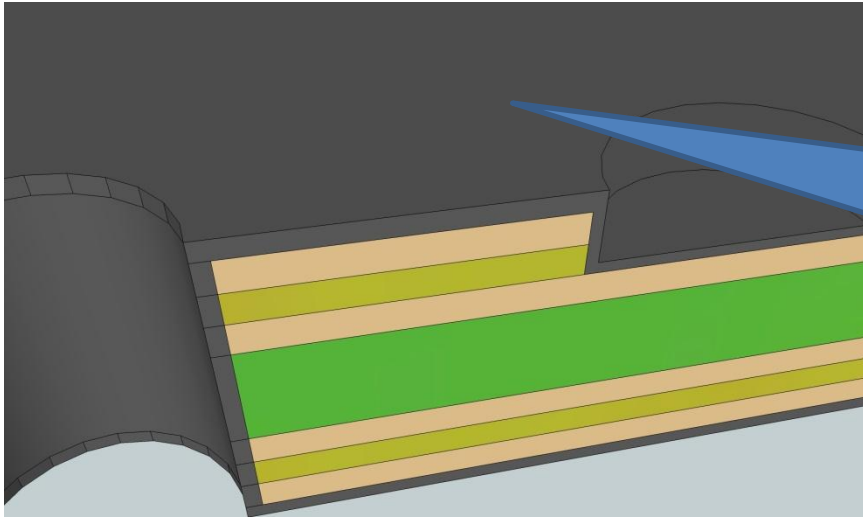


There still was some carbon from the activator !



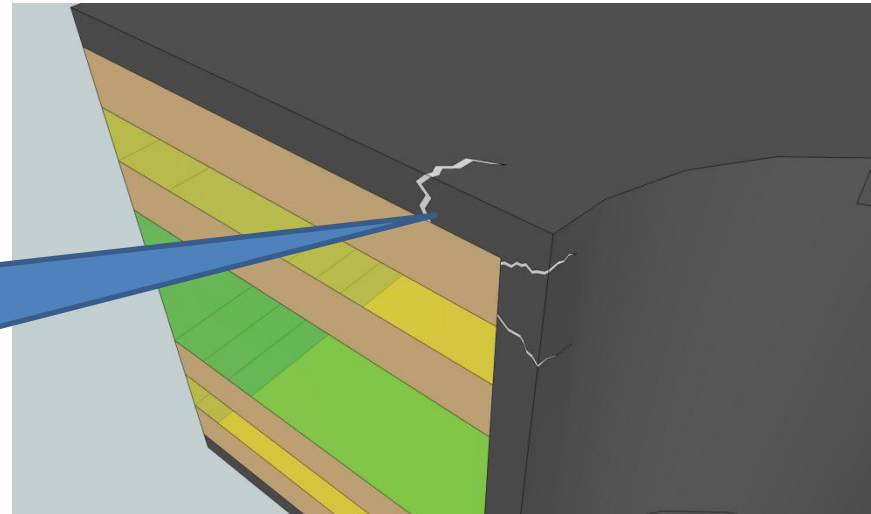
LPKF ViaCleaner

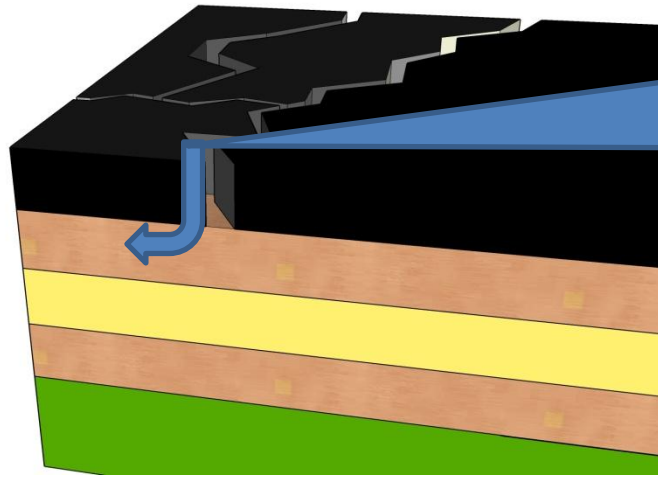
We will remove it.
Let us go back; **after** the activation, but **before** we put the board in the Copper Plate tank



The activator is covering the whole board

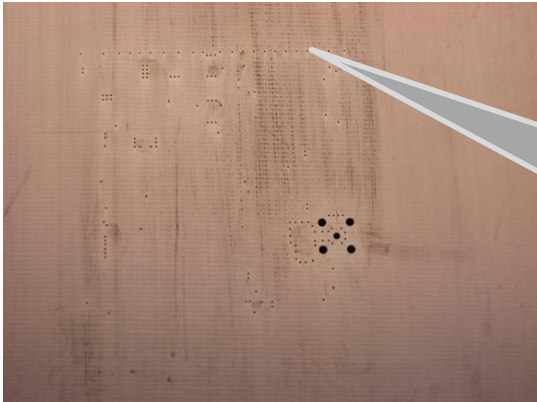
But the activator clad has some *microcracks*



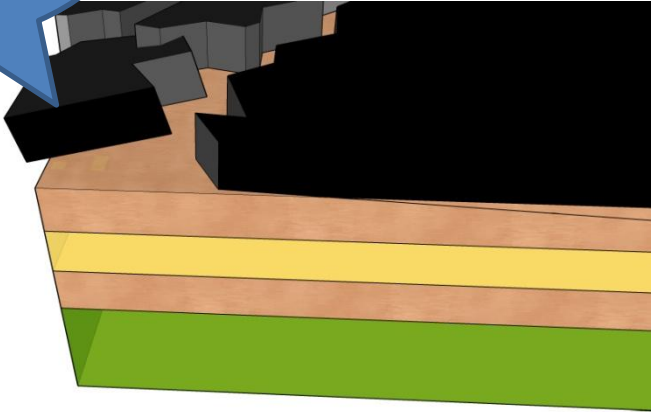


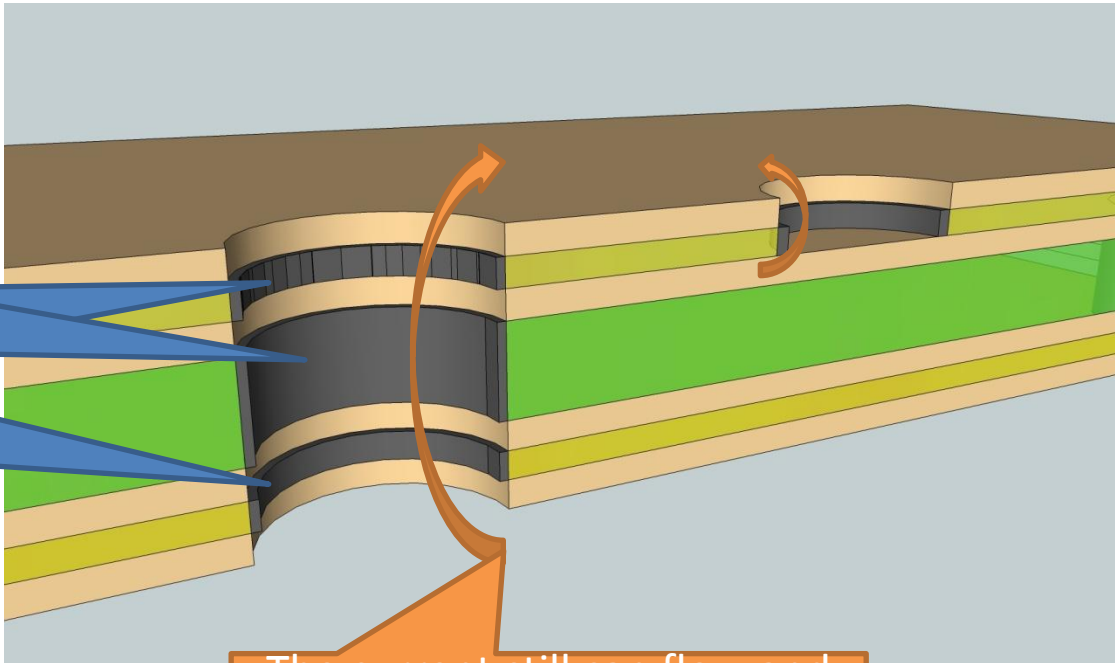
Through this cracks, the acid etches the copper underneath very slightly

and the activator falls off



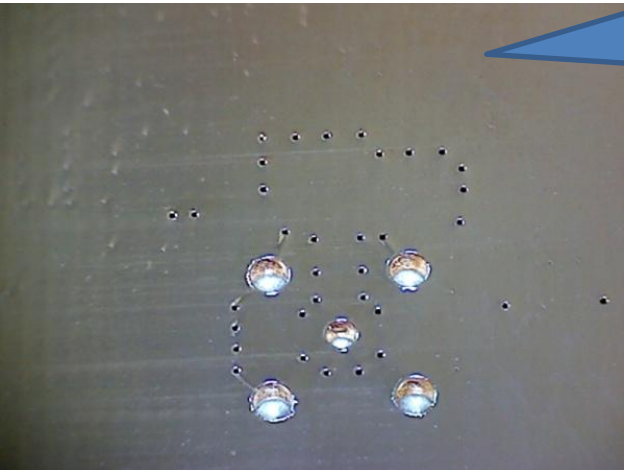
The board surface is much smoother now





It remains only in the regions where the substrate is underneath

The current still can flow and start the galvanic process



The quality of the plating is much better now...

specially at the blind vias

